TR-72D

RF Transceiver Module

Data Sheet

Preliminary



© 2017 IQRF Tech s.r.o. www.iqrf.tech www.iqrf.org Datasheet_TR-72D_170823 Page 1



Description

TR-72D is a family of IQRF transceiver modules operating in the 868 MHz and 916 MHz license free ISM (Industry, Scientific and Medical) frequency band. Its highly integrated ready-to-use design containing MCU, RF circuitry, integrated LDO regulator, serial EEPROM, optional temperature sensor and optional on-board antenna requires no external components. Extended RF power results in higher RF range. Ultra low power consumption fits for battery powered applications. MCU with built-in operating system significantly reduces application development time. Optional DPA framework supports applications even without programming.

There is no difference between TR and DCTR transceiver versions from IQRF OS v4.02D. All TRs support both OS as well as DPA approaches.



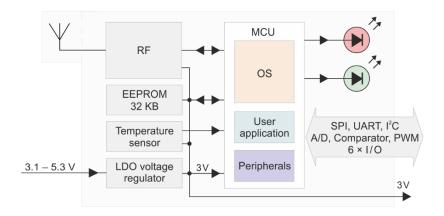
Key features

- Operating system (upgradeable at the user), easy to use
- DPA framework for Data controlled approach (formerly DCTR)
- GFSK modulation
- Selectable RF band 868 / 916 MHz, multiple channel
- RF output power 8 mW
- MCU with extended resources, user interrupt capability
- Extra low power consumption, power management modes
- SPI interface supported by OS in background
- Serial EEPROM 256 Kb
- PWM output
- Programmable HW timer
- +3 V LDO regulator output, battery monitoring
- 2 LEDs
- 8 pins, 6 I/Os
- A/D converter (2 channels), analog comparator
- Options: on-board antenna, U.FL connector, temperature sensor
- SIM card format, fits to KON-SIM-02 and KON-SIM-01 connectors
- Shielding can

Applications

- Bidirectional RF communication
- Point-to-point or network wireless connectivity
- Telemetry, AMR (automatic meter reading)
- WSN (wireless sensor network)
- · Building automation
- Street lighting control
- · Wireless monitoring, control and regulation
- · Remote data acquisition
- RF connectivity in many other fields
- Also for municipal and indoor areas
- · Internet of Things

Block diagram





Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications.

IQRF Tech MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND TO STATED CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE and disclaims all liability arising from this information and its use. Use of IQRF Tech devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless IQRF Tech from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any IQRF Tech intellectual property rights.

Electrical specifications

Typical values unless otherwise stated

Parameters specified in this datasheet are typical values. They are at power supply $V_{OUT} = 3 \text{ V}$ only. V_{OUT} voltage different from 3 V can impact on RF range and other parameters.

Supply voltage (V_{CC}) 3.1 V to 5.3 V

LDO output (V_{OUT}) +3 V ± 60 mV (V_{CC} > 3.1 V), 100 mA max.

Operating temperature ¹ -40 °C to +85 °C

Supply current

Deep sleep mode (OS v4.00 or higher only)

1.7 µA (all peripherals disabled ³, RF IC in Standby mode)

2.3 µA (all peripherals disabled ³, RF IC in Sleep mode)

Run mode

RF sleep 1.4 mA RF ready 2.8 mA

RX mode

 $\begin{array}{ccc} \text{STD} & & 12.1\,\text{mA} \\ \text{LP}^{\,4} & & 260\,\mu\text{A} \\ \text{XLP}^{\,4} & & 18.5\,\mu\text{A} \end{array}$

TX mode 8.3 mA – 21.5 mA (according to RF output power)

Additional LED supply current About 2 mA per LED. Rough value for brief guidance only.

RF band 868 MHz or 916 MHz (software configurable)

RF channels See IQRF OS User's guide, Appendix Channel maps

RF data modulation GFSK (Gaussian Frequency Shift Keying)

RF data transmission bit rate ⁵ 19.8 kb/s

RF sensitivity ⁶ -104 dBm (STD RX mode, checkRF (0))

RF output power 6,7A 9 dBm (for 50 Ω load), programmable in 8 levels (0 – 7).

Effective radiated power ^{7B} 6.5 dBm (868 MHz band), 2.0 to 6.5 dBm (916 MHz band). See *Diagrams 2A*, 2B.

RF interface 7A Single-ended, output impedance 50 Ω

Antenna ^{7B} PCB meander line, linear polarization, omnidirectional. See *Diagram 1*.

RF range ^{7B} 500 m ^{2A}, 1100 m ^{2B}

Input voltage on C1, C2, C5 to C8 pins 0 V to V_{OUT}

A/D converter 10 bit, 2 inputs. Refer to MCU datasheet.

Temperature sensor MCP9808E/MC (for TR types with 'T' postfix only, e.g. TR-72DT)

Size (L x W x H) 25.1 mm x 14.9 mm x 3.3 mm ^{7A} 31.8 mm x 14.9 mm x 3.3 mm ^{7B}

DE sense may about as with lawer temporative. Front condensation as by maidity area.

Note 1: RF range may change with lower temperature. Frost, condensation or humidity over 85% may disable module functionality. Transceiver suitability should be tested in final application at real conditions before volume use.

Note 2: Arrangement:

2A: Two TR-72DA transceivers plugged in DK-EVAL-04x kits, vertically, 1.6 m above the ground, in free space (with reflective planes at min. 100 m distance), bidirectional communication.

2B: Two TR-72DA transceivers plugged in DK-EVAL-04x kits through the RNG-EXT-01 adapters, vertically, 1.6 m above the ground, in free space (with reflective planes at min. 100 m distance), bidirectional communication.

Test software: E09-LINK example (STD mode, setRFpower(7), checkRF(0)), bit rate 19.8 kb/s.

Note 3: Additional current is consumed when a peripheral (e.g. watchdog, Brown-out detection etc.) is enabled.

Note 4: Depends on interferences.

Note 5: Several RF bit rates different from 19.8 kb/s will be available in future IQRF OS versions.

Note 6: RF circuitry and RF balun included, built-in PCB antenna not included.

Note 7: 7A: For TR types without built-in antenna.

7B: For TR types with built-in antenna.



Absolute maximum ratings

Stresses above listed maximum values may cause permanent damage to the device and affect device reliability. Functional operation at these or any other conditions beyond those specified is not supported.

Supply voltage (Vcc)

Voltage on C1, C2, C5 to C8 pins (configured as inputs) vs. GND

Storage temperature

Ambient temperature under bias

5.5 V

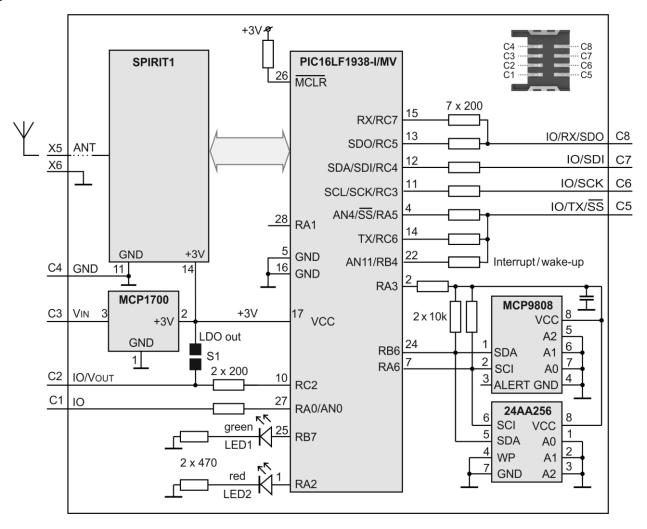
-0.3 V to (Vout + 0.3 V)

-40 °C to +85 °C

-40 °C to +85 °C

Caution: Electrostatic sensitive device. Observe appropriate precautions for handling.

Simplified schematic



Basic components

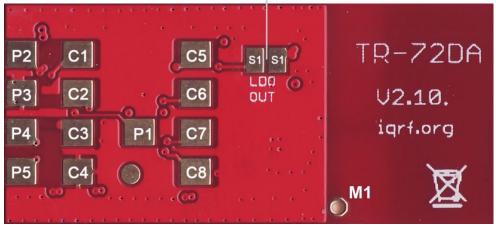
IC	Туре	Manufacturer	Note
MCU	PIC16LF1938–I/MV	Microchip	
RF IC	SPIRIT1	STMicroelectronics	
RF balun	BALF-SPI-01D3	STMicroelectronics	
LDO voltage regulator	MCP1700T-3002E/TT	Microchip	
Temperature sensor	MCP9808E/MC	Microchip	For types with 'T' postfix only, e.g. TR-72DT
EEPROM	24AA256-I/CS16K	Microchip	256 Kb

For more information refer to datasheets of ICs used.



Pin	Name	Description			
C1	IO/ADC/C-IN RA0 AN0 C12IN0	N General I/O pin Analog A/D input Comparator –input			
C2	IO/VOUT RC2 VOUT	General I/O pin (when S1 disconnected) On-board +3 V LDO output (when S1 connected)			
C3	VIN	Power supply voltage			
C4	GND	Ground			
C5 IO/ADC/TZ RA5 -SS AN4 C2OUT		-SS / PWM / COUT General I/O pin, SPI Slave select Analog A/D input Comparator output			
	RC6 TX CCP3	General I/O pin UART TX PWM output			
	RB4 AN11	General I/O pin, with programmable pull-up and interrupt/wake-up on change (IOC), RFPGM termination Analog A/D input			
C6	IO/SCK/SCL RC3 SCK SCL				
C7	IO/SDI/SDA RC4 SDI SDA	General I/O pin. Used as input during initial about 200 ms boot-up (after power supply rising-up) to recognize programming mode. SPI data I ² C data			
C8	IO/RX/SDO RC5 SDO				
	RC7 RX	General I/O pin UART RX			
X5	ANT	Antenna input			
X6	GND	Ground			
P1-P5		For manufacturer only			
S1		LDO output enable. Interconnect both S1 pads to enable. Default (from factory) disabled.			
M1		A hole for possible mechanical fixation			

Connect to enable LDO output



Bottom view



RF range

RF range strongly depends on the following design aspects:

- Hardware:
 - Construction of the devices (especially TR location within the device, PCB layout, ground planes, conductive areas and bulk objects such as metallic parts and batteries in the nearest surroundings, with respect to possible reflections and counterpoise effect)
 - Physical arrangement of devices (especially mutual orientations of antennas with respect to polarizations and radiation patterns)
- · Application software:
 - RF output power is selectable from 8 levels
 - To increase immunity against RF noise, incoming RF signal can be filtered according to signal strength.

Refer to IQRF OS Reference guide, function checkRF and Application note AN014 RF range optimizing at TR-7xDx transceivers.

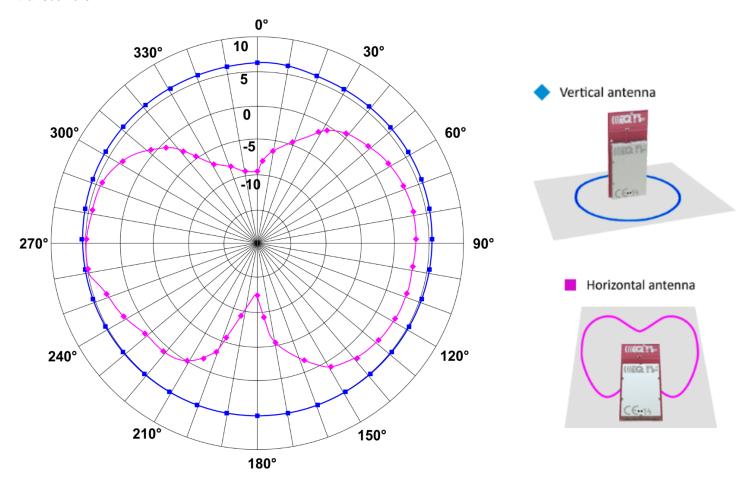
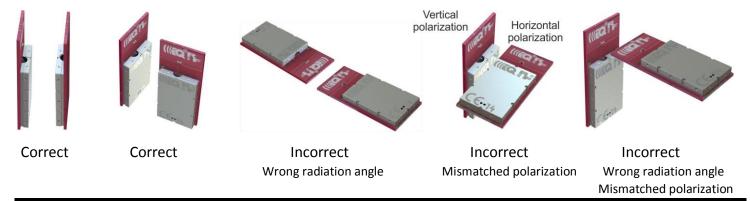


Diagram 1: TR-7xDA RF output power [in dBm] vs. antenna orientation (radiation patterns).

Examples of correct and incorrect arrangement of TR-72DA pairs:



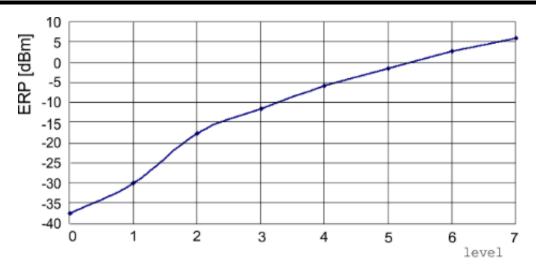


Diagram 2A: Effective radiated power (ERP) vs. level in the setRFpower (level) function. TR-72DA, 868 MHz band, channels 0 to 67. Refer to IQRF OS Reference guide.

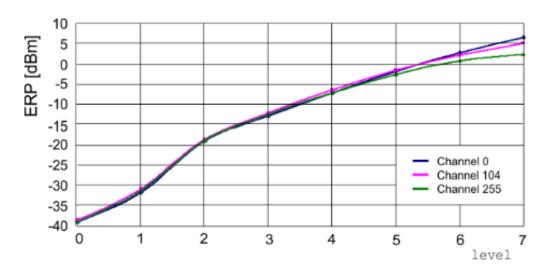


Diagram 2B: Effective radiated power (ERP) vs. level in the setRFpower (level) function. TR-72DA, 916 MHz band. Refer to IQRF OS Reference guide.

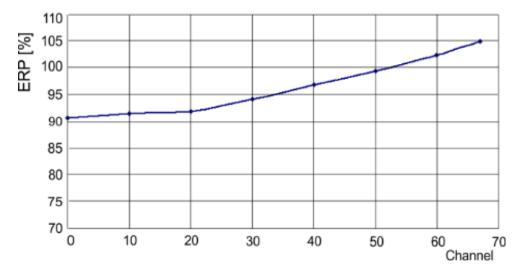


Diagram 3A: Relative effective radiated power (ERP) vs. channel, TR-72DA, 868 MHz band, with respect to channel 52 (100 %).

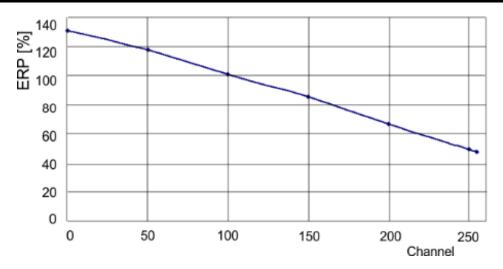


Diagram 3B: Relative effective radiated power (ERP) vs. channel, TR-72DA, 916 MHz band, with respect to channel 104 (100 %).

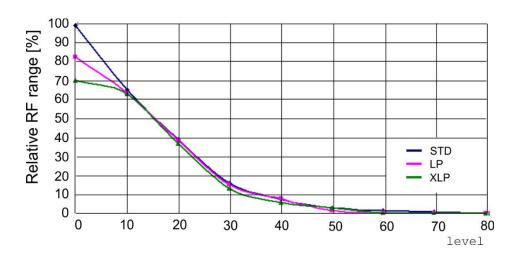


Diagram 4: Relative RF range vs. level in the checkRF (level) function in STD, LP and XLP RX modes. Refer to IQRF OS Reference guide, function checkRF ().

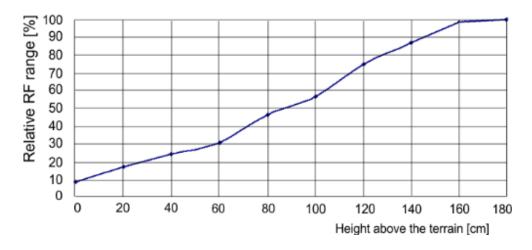
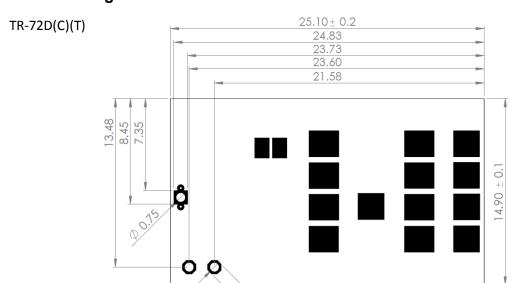


Diagram 5: TR-72DA relative RF range vs. antenna height above the ground, 868 MHz and 916 MHz band.

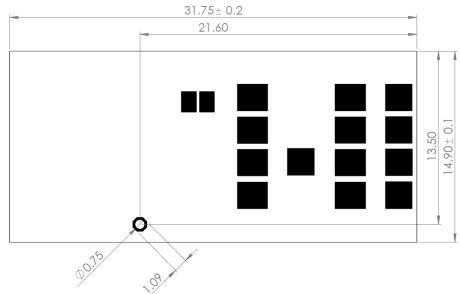
© 2017 IQRF Tech s.r.o. www.iqrf.tech www.iqrf.org Datasheet_TR-72D_170823 Page 8



Mechanical drawings







Top view, Units: mm

Hardware revision

• TR-72D(A) v2.14 Minor improvements to optimize production.

• TR-72DA v2.13 Minor improvements to optimize production.

• TR-72D(A) v2.12 Minor HW changes. TR-72DA parts suitable also for 916 MHz band are marked "868/916" by laser.

• TR-72DA v2.11 EAP samples, minor HW changes.

• TR-72D v2.10 EAP samples, standard dimensions.

• TR-72DA v2.02 EAP samples, length 33.8 mm.

• TR-72DA v2.01 EAP samples, limited RF range.

© 2017 IQRF Tech s.r.o. www.iqrf.tech www.iqrf.org Datasheet_TR-72D_170823 Page 9



Application

Users have to ensure observing local provisions and restrictions relating to the use of short range devices **by software**, e.g. the CEPT ERC/REC 70-03 Recommendation and subsequent amendments in EU.

See IQRF video tutorial set on www.iqrf.org/videos.

Assembly

TR-72Dx modules should be mounted in SIM connector. They are not intended for SMT reflow soldering. Recommended SIM connector: KON-SIM-02 or KON-SIM-01. It is not allowed to connect wires to pads (except of the X5 and S1 pads) by soldering.

Sealing

In case of sealing or protecting TR modules against a harsh environment by coating, encapsulating or potting using a lacquer, gel or other filling matter, the ion cleanless of the TR modules must be less than 1 μ g/cm² of NaCl equivalent otherwise there is a risk of corrosion.

Such a surface treatment always impacts the RF range. Thus, sealing material should have relative permeability (μ_r) as close to 1 within given frequency band. E.g. $\mu_r = 4$ at 868 MHz decreases reletive range to cca 70%.

Protecting materials, methods, accomplishments and handling must comply with general requirements and rules for proper use with electronic devices. Damaging, either chemical or mechanical (even due to the thermal expansivity of the material used) must be avoided. Testing is necessary to ensure that the application meets with specifications.

Operating system

See IQRF OS User's guide and IQRF OS Reference guide.

DPA framework and DCTR

See DPA Framework technical guide.

Application software

See IQRF Quick start guide and IQRF application examples.

Programming (upload)

There are the following possibilities to upload an application program in TR-72Dx modules:

- Wired upload with TR-72Dx plugged via the SIM connector in the CK-USB-04(A) programmer.
- For TR-72Dx modules populated in an application:
 - · Wired upload
 - Using the CK-USB-04A programmer. See the CK-USB-04A User's guide.
 - Using the CK-USB-04 programmer and the KON-TR-01P adapter. See the KON-TR-01P User's guide.
 - Wireless upload: See the IQRF OS User's guide, Appendix RFPGM RF programming™.

Transceiver series. TR/DCTR are not differentiated from IQRF OS v4.02D.



Product information

Ordering codes

Peripheral options

nil - No other option

T - Temperature sensor

Antenna options

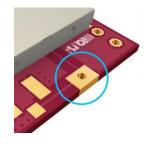
nil - soldering pad-hole (no antenna, no U.FL connector)

A - PCB antenna

C - U.FL connector (mini coax)

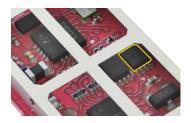
Туре	Antenna connection	Data controlled	Temperature sensor
TR-72D	Soldering pad-hole	Yes	_
TR-72DC	U.FL connector	Yes	_
TR-72DA	PCB antenna	Yes	_

Туре	Antenna connection	Data controlled	Temperature sensor
TR-72DT Soldering pad-hole		Yes	Yes
TR-72DCT	TR-72DCT U.FL connector		Yes
TR-72DAT PCB antenna		Yes	Yes









TR-72D

TR-72DC

TR-72DA

TR-72DT

Document history

• 170823 Updated for IQRF OS v4.02D.

 170810 Updated for TR/DCTR fusion from IQRF OS v4.01D. Mechanical drawings and Recommended PCB layout updated. TR size rounded to 25.1 mm in chapter *Electrical specifications*. *Diagram 4* updated. Some minor improvements.

170322 Diagrams 3A and 3B added. Preliminary.

170314 Updated for HW v2.14 and IQRF OS v4.00 (preliminary). Electrical specification revised. Chapter Sealing added. Chapter RF range revised. Variances in mechanical drawings slightly precised. Some minor improvements.

160302 Notice about local provisions added to chapter Application.

• 160219 More detailed RF range specification. C7 and C8 pin description extended.

151005 ETSI directives updated.

150810 Revised. Preliminary.

140430 Preliminary.



Sales and Service

Corporate office

IQRF Tech s.r.o., Prumyslova 1275, 506 01 Jicin, Czech Republic, EU Tel: +420 493 538 125, Fax: +420 493 538 126, www.iqrf.tech

E-mail (commercial matters): sales@iqrf.org

Technology and development

www.iqrf.org

E-mail (technical matters): support@iqrf.org

Partners and distribution

www.iqrf.org/partners

Quality management

ISO 9001: 2009 certified

Complies with ETSI directives EN 301489-1 V1.9.2:2011, EN 301489-3 V1.6.1:2013, EN 300220-1 V2.4.1:2012, EN 300220-2 V2.4.1:2012 and VO-R/10/05.2014-3.

Complies with directives 2011/65/EU (RoHS) and 2012/19/EU (WEEE).



Trademarks

The IQRF name and logo are registered trademarks of IQRF Tech s.r.o.

PIC, SPI, Microchip and all other trademarks mentioned herein are property of their respective owners.

Legal

All information contained in this publication is intended through suggestion only and may be superseded by updates without prior notice. No representation or warranty is given and no liability is assumed by IQRF Tech s.r.o. with respect to the accuracy or use of such information.

Without written permission, it is not allowed to copy or reproduce this information, even partially.

No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

The IQRF® products utilize several patents (CZ, EU, US).

On-line support: support@iqrf.org

